

AMENDMENTS TO THE SPECIFICATION

Please amend the fourth paragraph on page 5 as follows:

Lastly, a retainer ring is provided. The retainer ring ~~[[is]]~~ has a third internal diameter and is configured to couple together the lens and the plate and the mounting base.

Please amend the first paragraph on page 13 as follows:

Lastly a retainer ring 70 is provided. The retainer ring ~~[[is]]~~ has a third internal diameter and is configured to couple together the lens and the plate and the mounting base.

Please amend the last paragraph of page 14 beginning on line 14 and spanning to line 4 of Page 15 as follows:

Emitter are affixed to ~~[[thermal]]~~ thermal conductive circuit boards in a manner that facilitates heat conduction from emitter to board. This mode of heat transfer forms the novelty of this invention since prior art uses a more costly, less efficient, cylindrical heat sink to remove heat from the emitters. In practice, the emitter has a large scale surface mount component that is soldered to electrically conductive traces on the board. Thermal contact is ensured by the use of thermally conductive paste which is applied between the emitter and the board. ~~[[IN]]~~ In addition, the solder tabs of each emitter removes heat from the emitter and conveys this heat to

solder pads on the circuit board. Heat generated by emitter must be removed to the environment to preclude failure or reduced light output.

Please amend the paragraph beginning on line 5 of page 15 as follows:

Heat ~~collect~~ collected by the circuit board is transported to the environment through convective and conductive means. Convective heat loss is realized by heating the air confined within the lens, which circulates exchanging heat with the plastic or the glass lens. The lens dissipates heat to the environment primarily by convection. Conductive heat loss is realized by thermally conductive path through the length of the circuit board.

Please amend the paragraph beginning on line 13 of page 15 as follows:

Thermally conductive ~~[[paste]]~~ paste is applied at the interface of the boards and the plate to maximize heat transfer. The circular plate is fabricated of a thermally conductive composition and may comprise an aluminum disk or a circular J-P Clad thermally conductive circuit board having electrical circuit components mounted thereto. Heat reaching the plate is transferred to the base and the ring by maintaining good thermal

contact. The base and ring heat is dissipated to the environment through convective process and mounting arrangements.